TOSHIBA LED LAMP

TLG102AKB, TLG102AKW, TLG108AKB, TLG108AKW, TLR102AKB TLR102AKW, TLR108AKB, TLR108AKW, TLR109AKB, TLR109AKW

LED LAMP WITH HOLDER

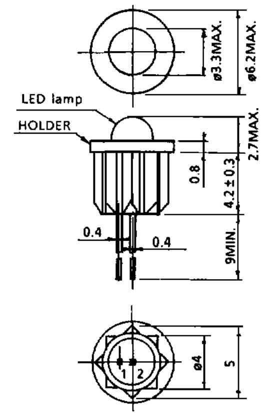
- Resin stem type LED lamp with holder can easily be mounted into the drill hole on a panel.
- Two types of holder colors are available. These are distinctive by suffix type No.

HOLDER COLOR	SUFFIX TYPE No.
White	KW
Black	KB

- The characteristic of LED lamp with holder are same as the original LED lamps.

PRODUCT NAME	LED LAMPS WITH BRACKET
TLG102AKB	TLG102A
TLG102AKW	
TLG108AKB	TLG108A
TLG108AKW	
TLR102AKB	TLR102A
TLR102AKW	
TLR108AKB	TLR108A
TLR108AKW	
TLR109AKB	TLR109A
TLR109AKW	

Unit in mm



1. ANODE
2. CATHODE

JEDEC	—
EIAJ	—
TOSHIBA	4-3F2A

MAXIMUM RATINGS (Ta = 25°C)

PRODUCT NAME	FORWARD CURRENT I_F (mA)	REVERSE VOLTAGE V_R (V)	POWER DISSIPATION P_D (mW)	OPERATING TEMPERATURE T_{opr} (°C)	STORAGE TEMPERATURE T_{stg} (°C)
TLG (102A / 108A) KB / KW	30	4	85	−20~75	−30~75
TLR (102A / 108A / 109A) KB / KW	25	4	70	−20~75	−30~75

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HANDLING PRECAUTIONS

- Soldering temperature≦260°C ; Soldering time≦3s (Up to 2mm from the body of the device).
- If the lead is formed, the lead should be formed up to 2mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- Use the printed circuit boards thickness are 4mm or less.
- Holes in the printed circuit boards are 4.7mm diameter.

(Note) This product is made to order.